

### ● General Description

The AGM1075D combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$

This device is ideal for load switch and battery protection applications.

### ● Features

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

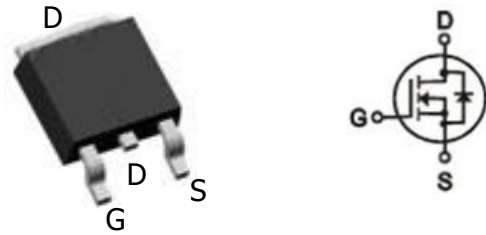
### ● Application

- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

### Product Summary

BVDSS	RDSON	ID
100V	55mΩ	16A

### TO-252 Pin Configuration



### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM1075D	AGM1075D	TO-252	330mm	16mm	2500

**Table 1. Absolute Maximum Ratings (TC=25°C)**

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	100	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25°C) (Note 1)	16	A
	Drain Current-Continuous(Tc=100°C)	10	A
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 2)	62	A
PD	Maximum Power Dissipation(Tc=25°C)	35	w
	Maximum Power Dissipation(Tc=100°C)	13	w
EAS	Avalanche energy (Note 3)	10	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

**Table 2. Thermal Characteristic**

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	---	62.5	°C/W
RθJC	Thermal Resistance Junction-Case <sup>1</sup>	---	3.6	°C/W

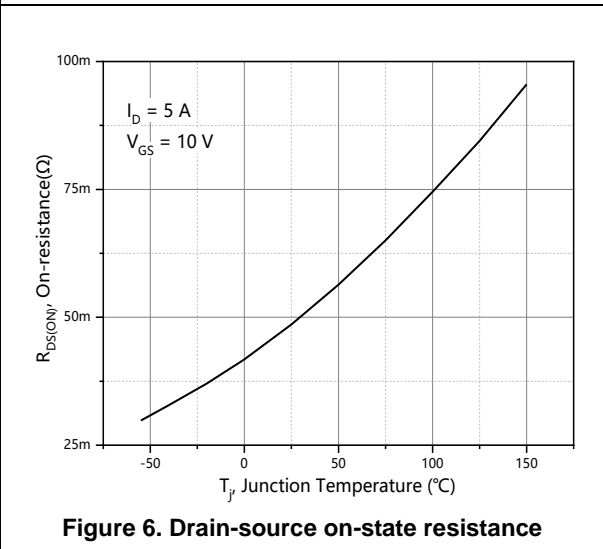
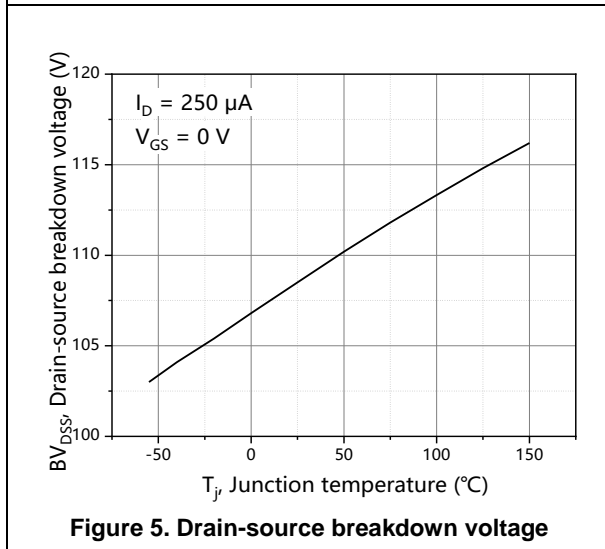
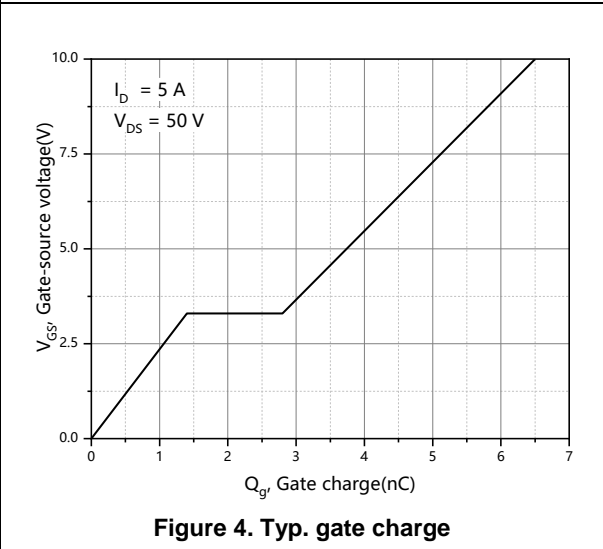
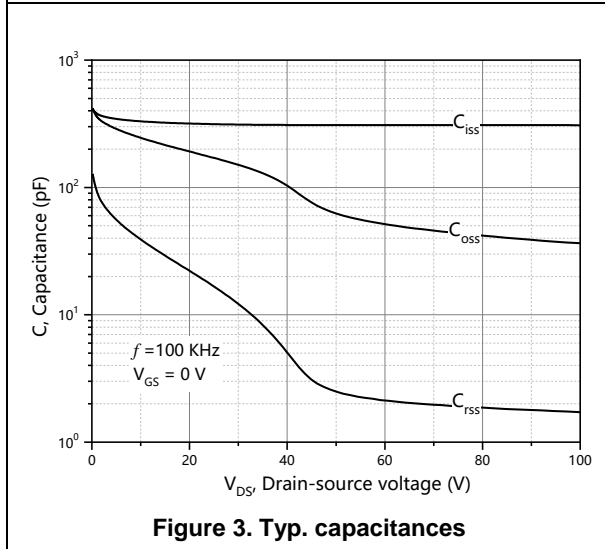
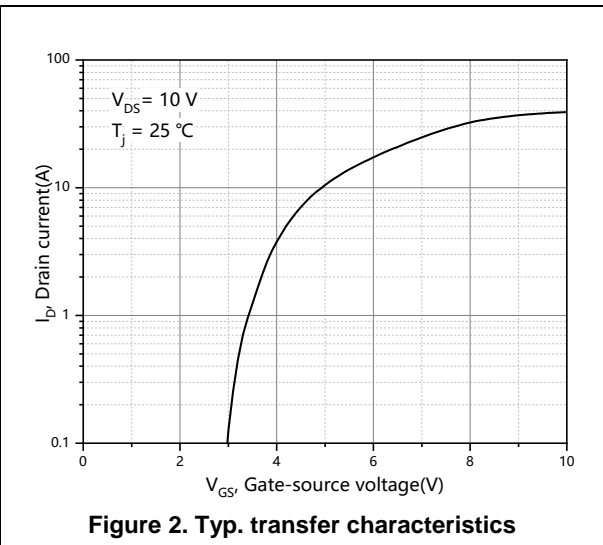
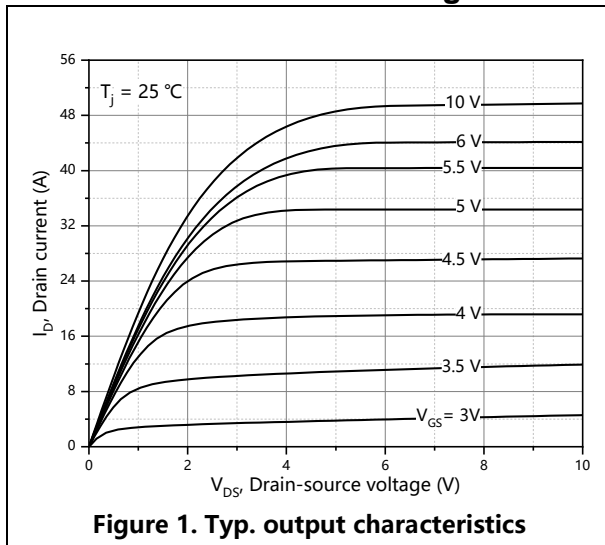
**Table 3. Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

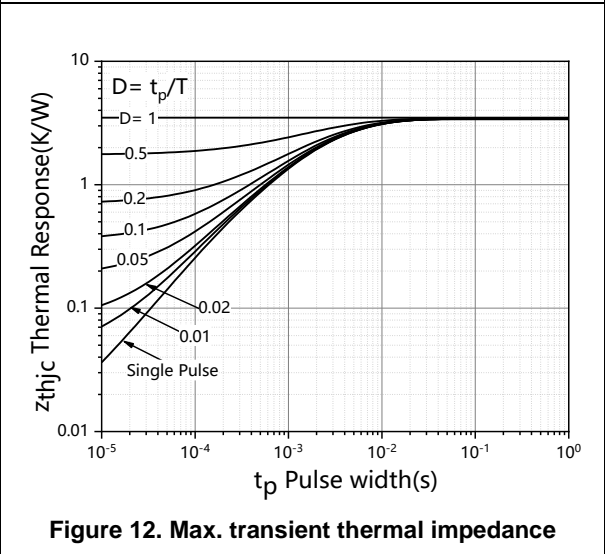
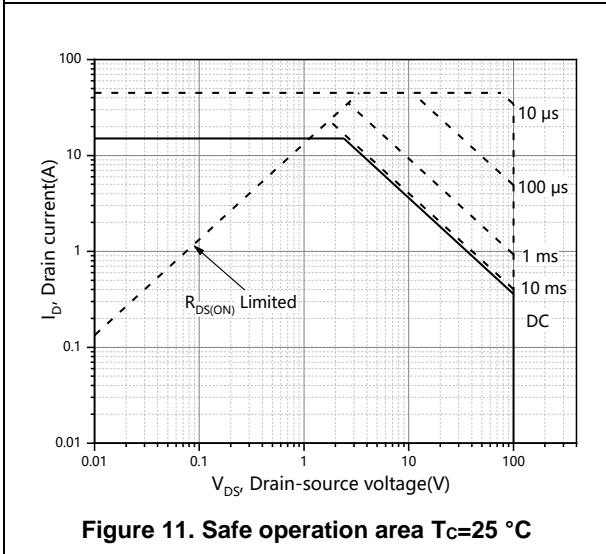
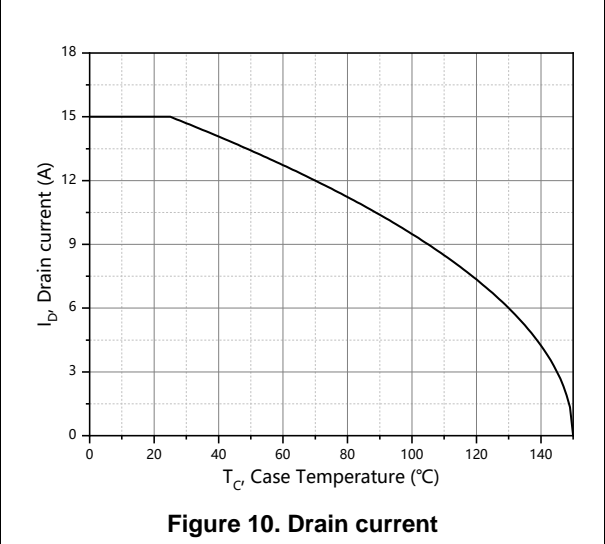
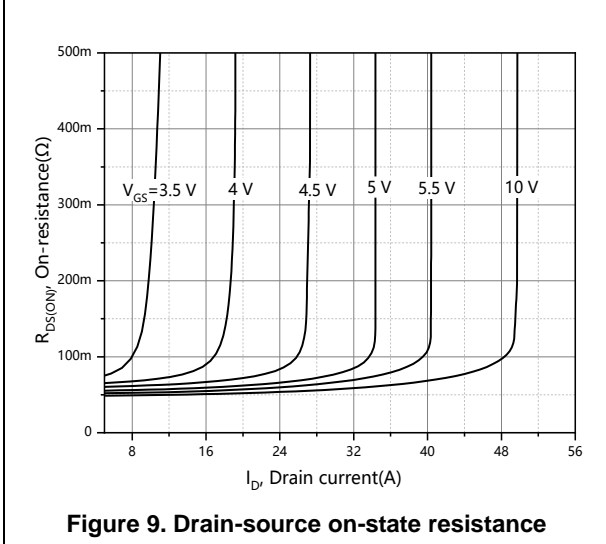
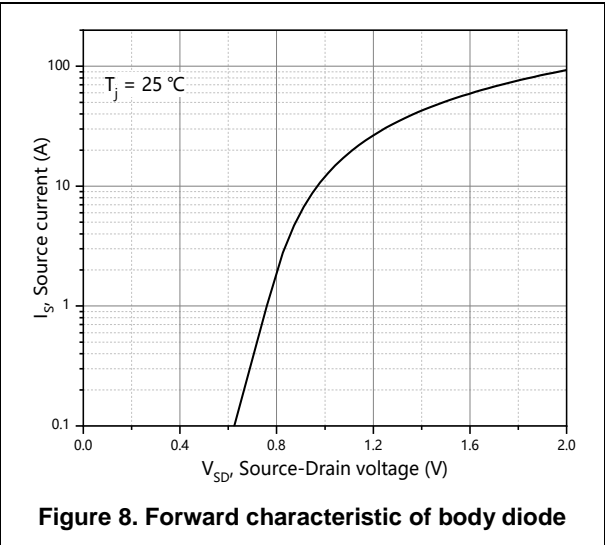
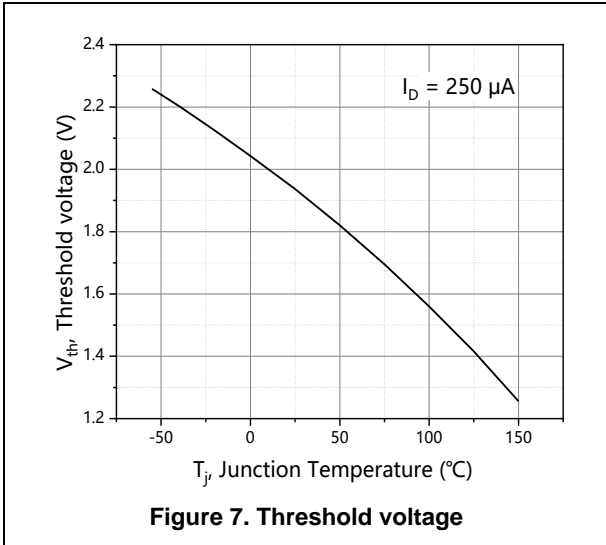
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	100	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=80V,VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	1.2	1.7	2.1	V
gFS	Forward Transconductance	VDS=5V,ID=3A	--	6	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=10A	--	55	75	mΩ
		VGS=4.5V, ID=3A	--	65	90	mΩ
<b>Dynamic Characteristics</b>						
Ciss	Input Capacitance	VDS=50V,VGS=0V, F=1MHZ	--	520	--	pF
Coss	Output Capacitance		--	40	--	pF
Crss	Reverse Transfer Capacitance		--	2.4	--	pF
Rg	Gate resistance	f=1.0MHz	--	--	--	Ω
<b>Switching Times</b>						
td(on)	Turn-on Delay Time	VGS=10V,VDS=50V, ID=10A,RGEN=6Ω	--	16.2	--	nS
tr	Turn-on Rise Time		--	3.2	--	nS
td(off)	Turn-Off Delay Time		--	13	--	nS
tf	Turn-Off Fall Time		--	22	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=50V, ID=12A	--	6	--	nC
Qgs	Gate-Source Charge		--	1.1	--	nC
Qgd	Gate-Drain Charge		--	1.3	--	nC
<b>Source-Drain Diode Characteristics</b>						
ISD	Source-Drain Current(Body Diode)		--	--	16	A
VSD	Forward on Voltage	VGS=0V,IS=10A	--	--	1.2	V
trr	Reverse Recovery Time	Isd=10A , dI/dt=100A/μs , TJ=25°C	--	45	--	ns
Qrr	Reverse Recovery Charge		--	63	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: T<sub>J</sub>=25°C

**Electrical Characteristics Diagrams**




Test circuits and waveforms

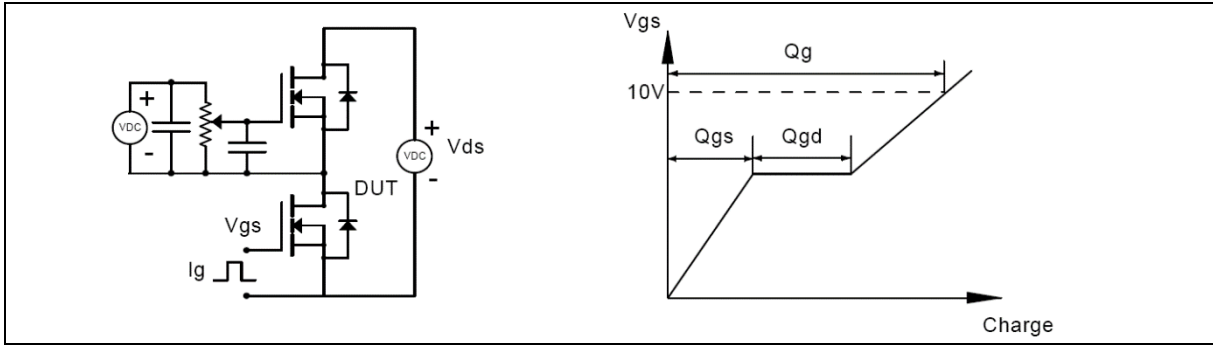


Figure 1. Gate charge test circuit & waveform

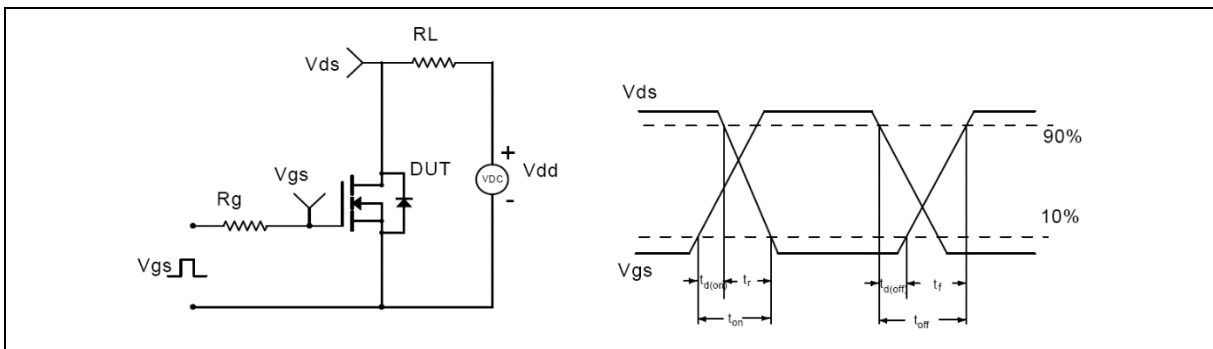


Figure 2. Switching time test circuit & waveforms

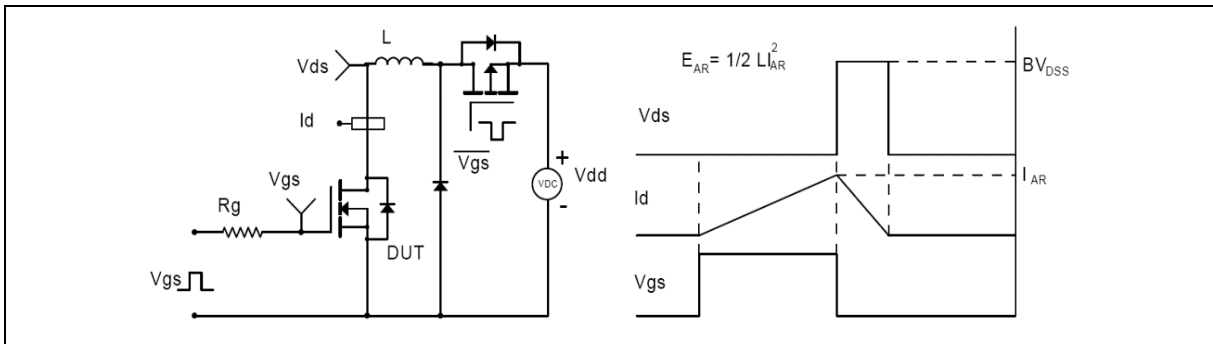


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

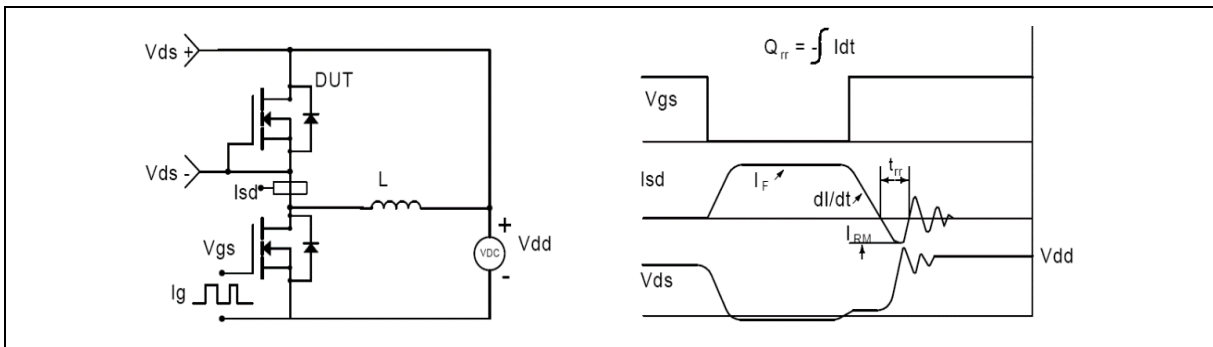
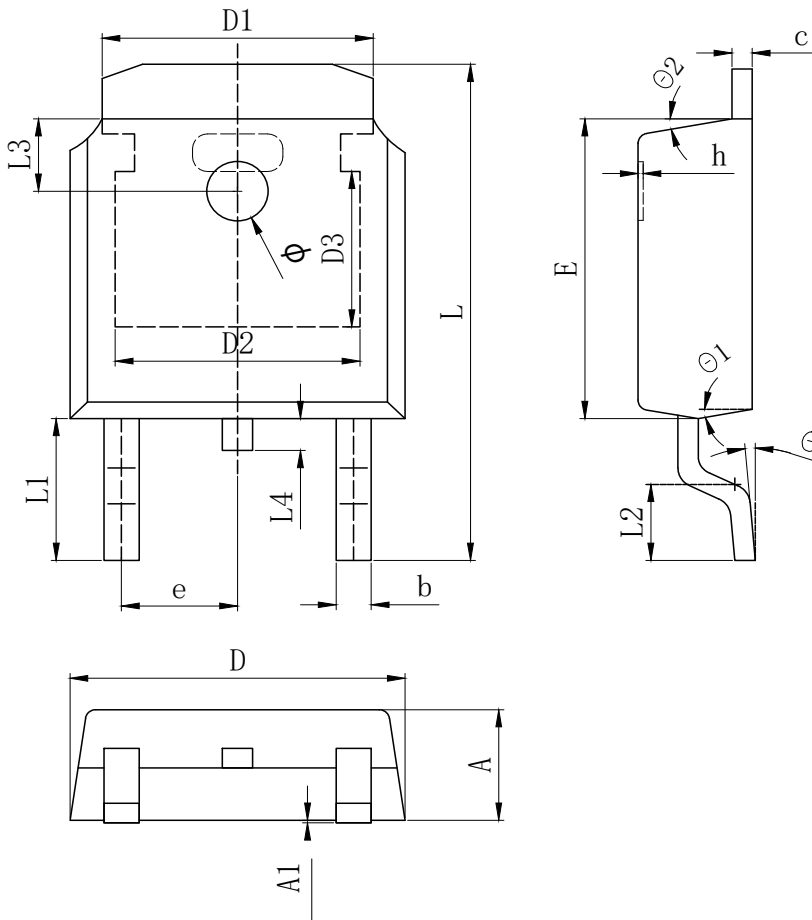
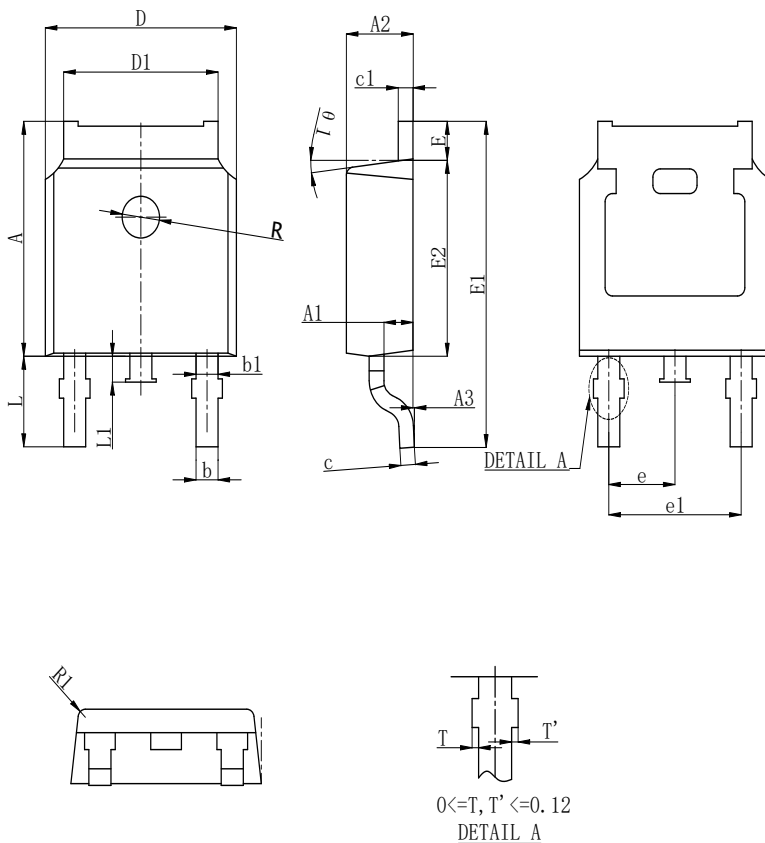


Figure 4. Diode reverse recovery test circuit & waveforms

## TO-252 Package Outline Data



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
$\phi$	1.100	1.200	1.300
$\theta$	0°		8°
$\theta 1$	9° TYP		
$\theta 2$	9° TYP		



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	7.050	7.100	7.150
A1	0.960	1.010	1.060
A2	2.250	2.300	2.350
A3	0.000	0.050	0.100
b	0.760REF.		
b1	1.000REF.		
c	0.508REF.		
c1	0.508REF.		
D	6.550	6.600	6.650
D1	5.220	5.320	5.420
E	0.950	1.000	1.050
E1	9.700	9.900	10.100
E2	6.050	6.100	6.150
e	2.286BSC		
e1	4.572REF.		
L	2.650	2.800	2.950
L1	0.700	0.800	0.900
$\theta 1$	7° REF.		
R	1.300REF.		
R1	0.250REF.		


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